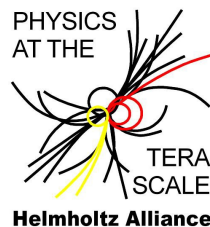


# Adhesives in silicon strip modules

## Glue evaluation and irradiation studies

Ingo Bloch, Heiko Lacker, Kristin  
Lohwasser, Dennis Sperlich, Luise Poley  
Title of Presentation  
PETTL-Meeting, December 1 2014

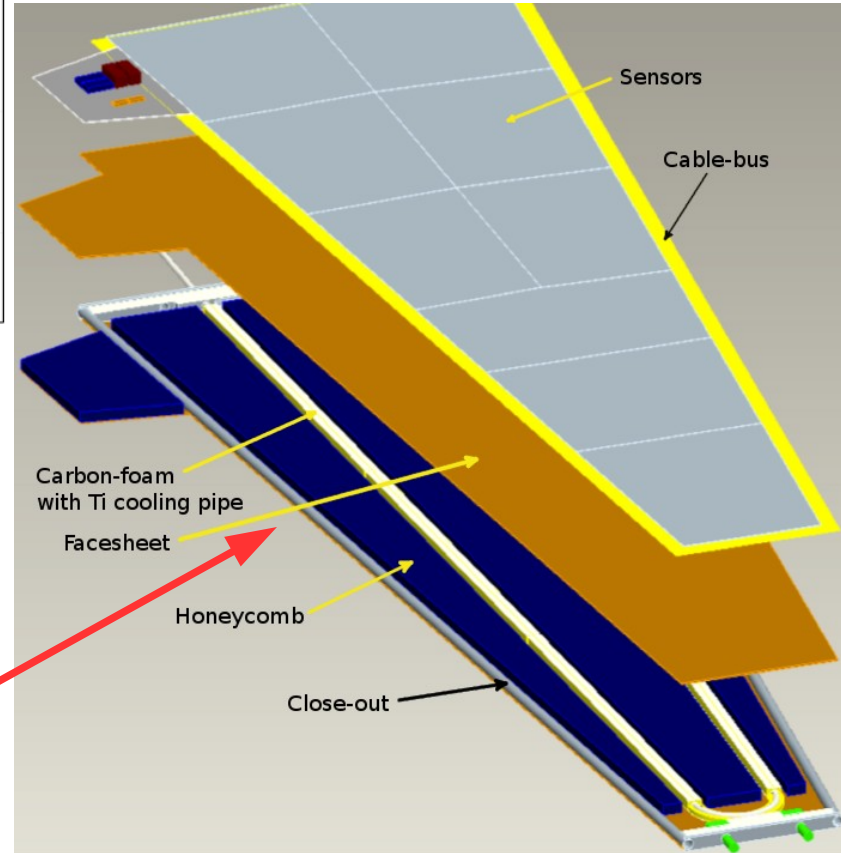
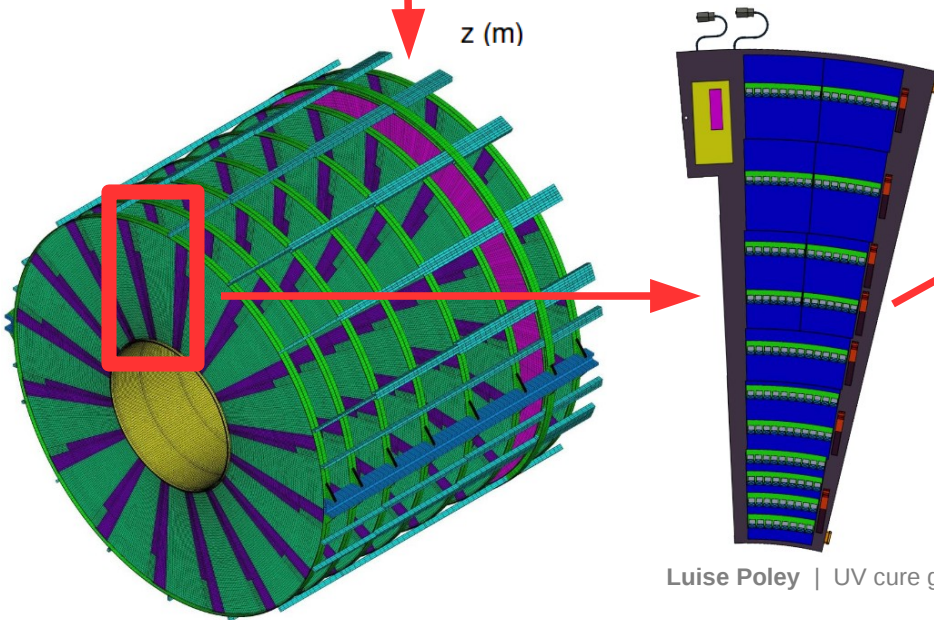
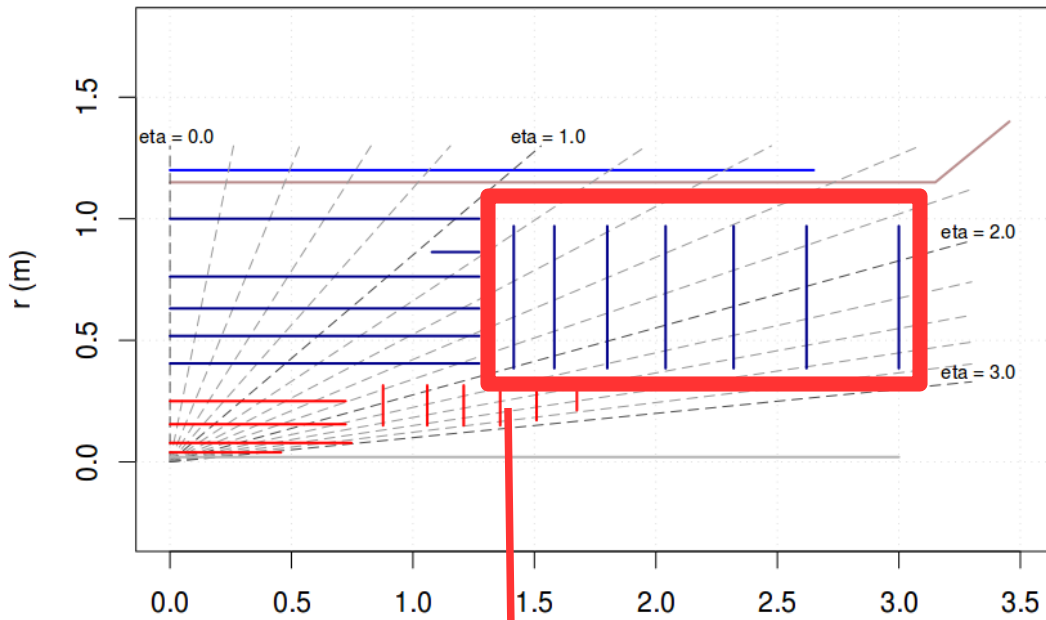


## Overview of ongoing glue studies

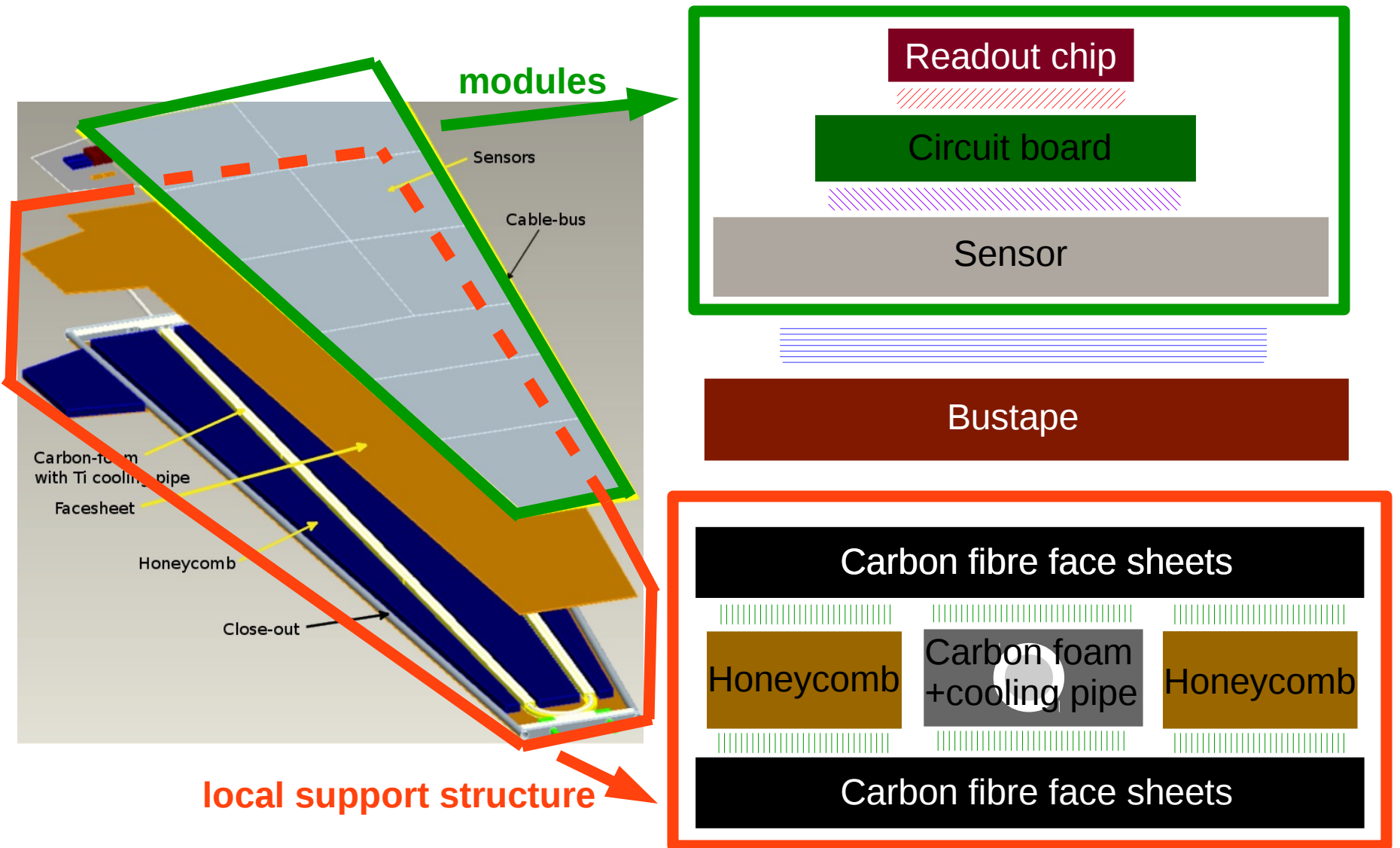
- > UV cure glue as replacement for silver epoxy glue
- > Glue characteristics
- > UV cure glue as replacement for optical glue on sensor



# Strip detector for the Atlas High-Luminosity Upgrade



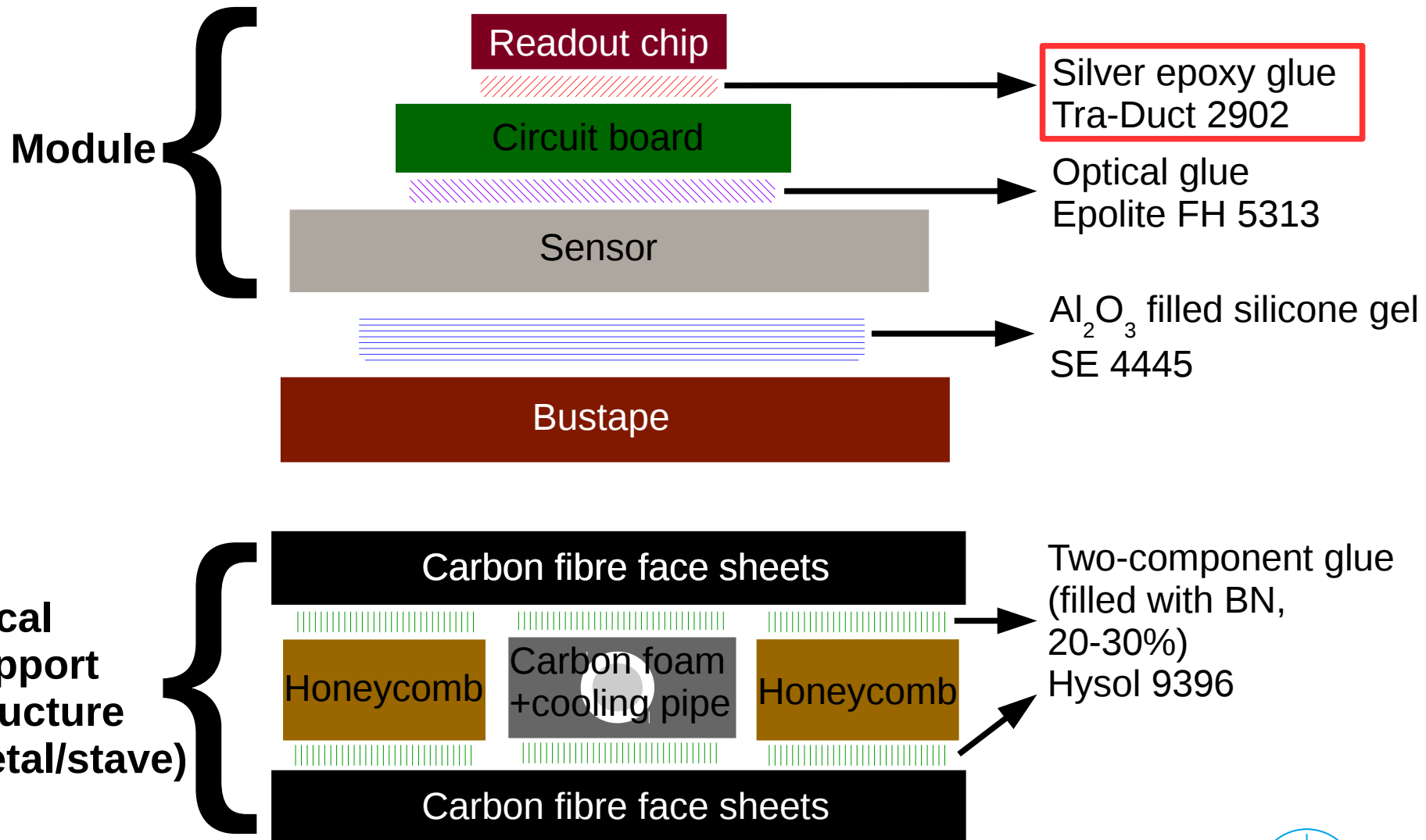
# Strip detector for the Atlas High-Luminosity Upgrade



## UV cure glue as replacement for silver epoxy glue

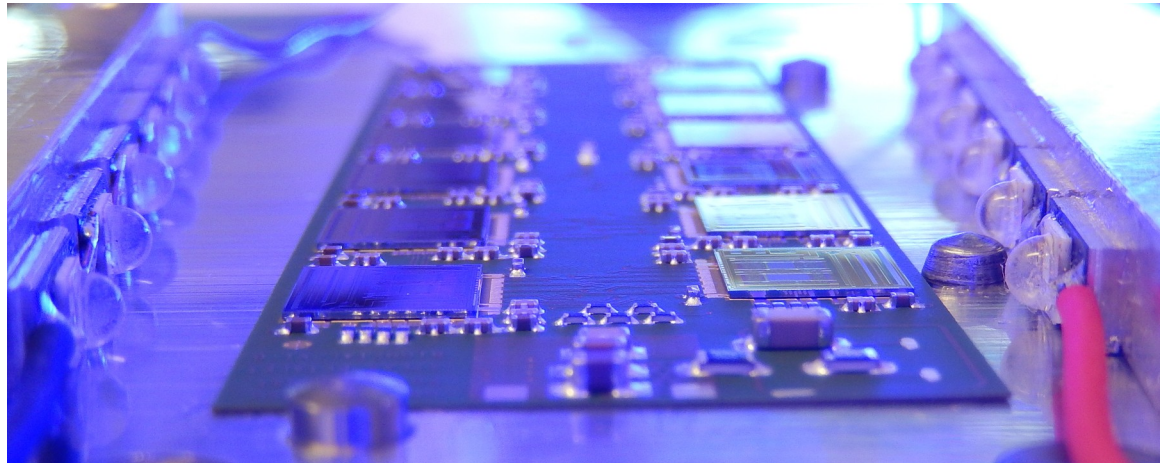


# Glues used in the detector



# UV cure glues between ASIC and hybrid: summary

- > Glue currently in use has issues (long curing time, expensive, short radiation length, high activation ...)
- > Seven possible alternatives (6 UV cure glues, 1 glue pad) selected (short curing time, sufficient working temperature range, low toxicity classification, cost-efficient ...)
- > Performed tests:
  - Dispensing
  - UV curing
  - Bonding
  - Corrosion
  - Irradiation
  - Thermal cycling
  - Thermal conduction
  - Shear strength
- > 3 good candidates remained (DYMAX 3013, 6-621, LOCTITE 3525)



# UV cure glues between ASIC and hybrid: summary

	Silver epoxy glue	UV cure glues (3 good candidates)
Cost	40 \$ for 2.65 g → 15.1 \$/g	400 \$ for 1l → 0.4 \$/g
Construction	Successfully used	Successfully used
Curing time	6 hours	10 minutes
Thermal conduction	good	good
Thermal cycling	no changes observed	no changes observed
Irradiation	no changes observed	thermal conduction and shear strength improved
Shear strength	> 50 N	> 50 N
Radiation length	1.3 cm	20 – 22 cm





# UV cure glues between ASICs and hybrid: currently

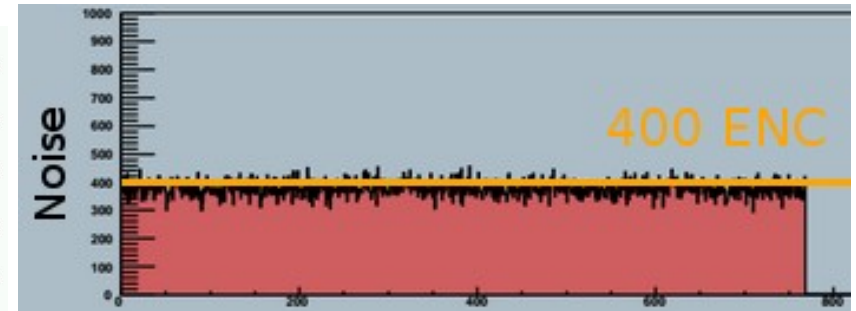
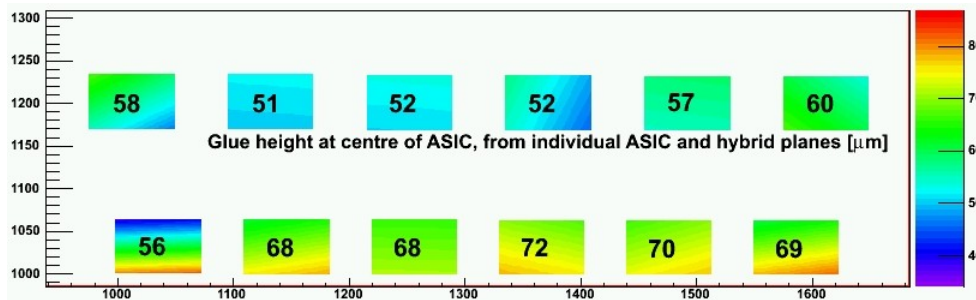
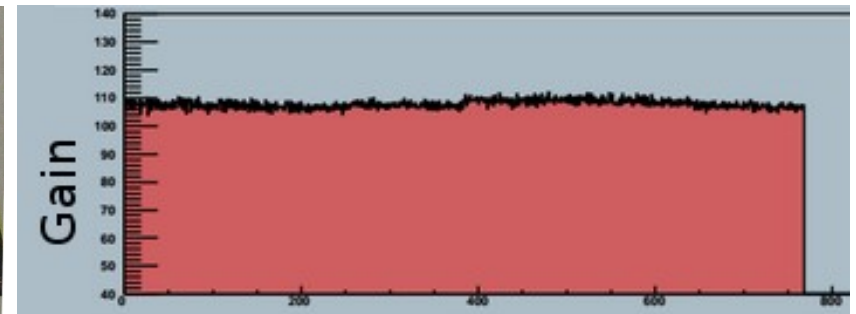
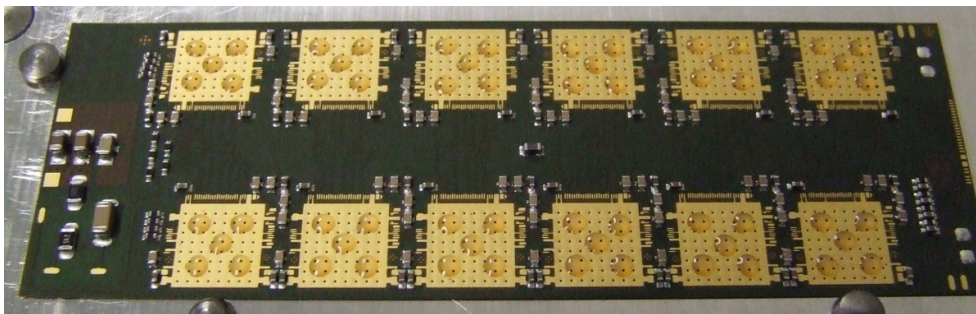
- > Chemistry in glues: organic (carbon chains, hydrogen bonds, ...)
- > Effects of irradiation probably depend on particle type and energy
- > Current investigation of different types of irradiation on glues
  - Previously: 23 MeV protons (KIT)
  - Next:
    - 800-900 MeV protons (Los Alamos), December 2014
    - Reactor neutrons (Ljubljana), soon
    - 23 GeV protons (CERN), 2015?
- > Shear tests of all samples to be performed after irradiations

**In progress**



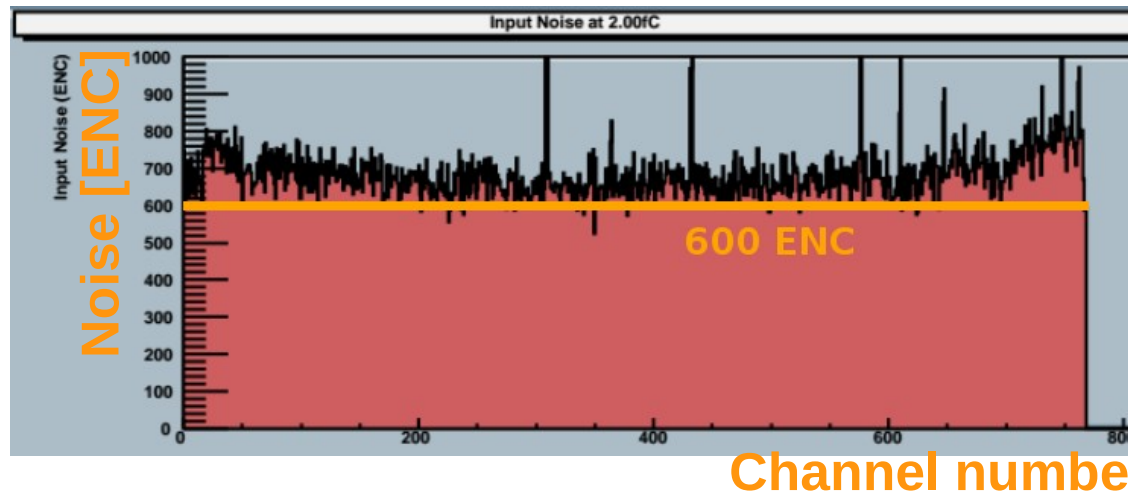
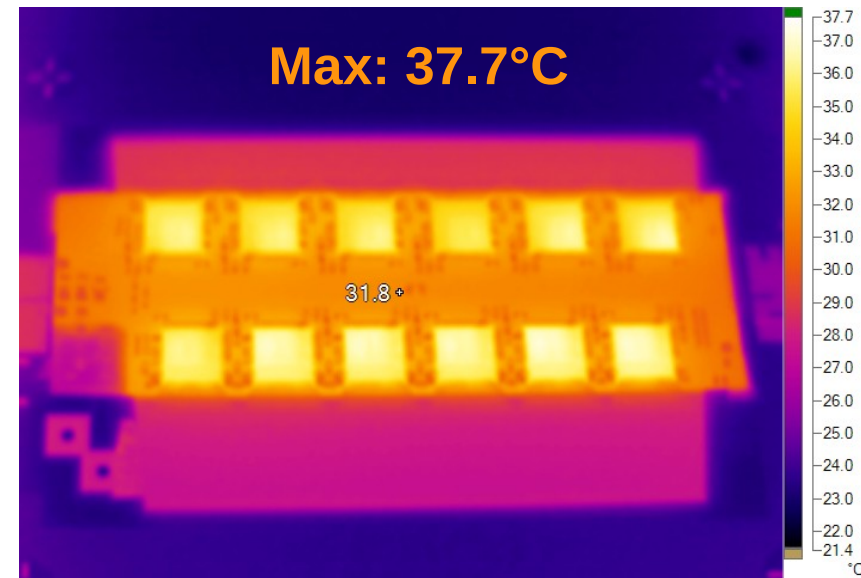
# UV cure glues between hybrid and ASICs: first hybrid

- > First hybrids built using UV cure glues
  - Dispensed with microliter pipette at DESY
  - Dispensed with fully automatic glue dispenser in Birmingham
  - Dispensing tests in progress in Glasgow
- > Hybrids can be operated, show good results and do not overheat



# UV cure glues between hybrid and ASICs: first module

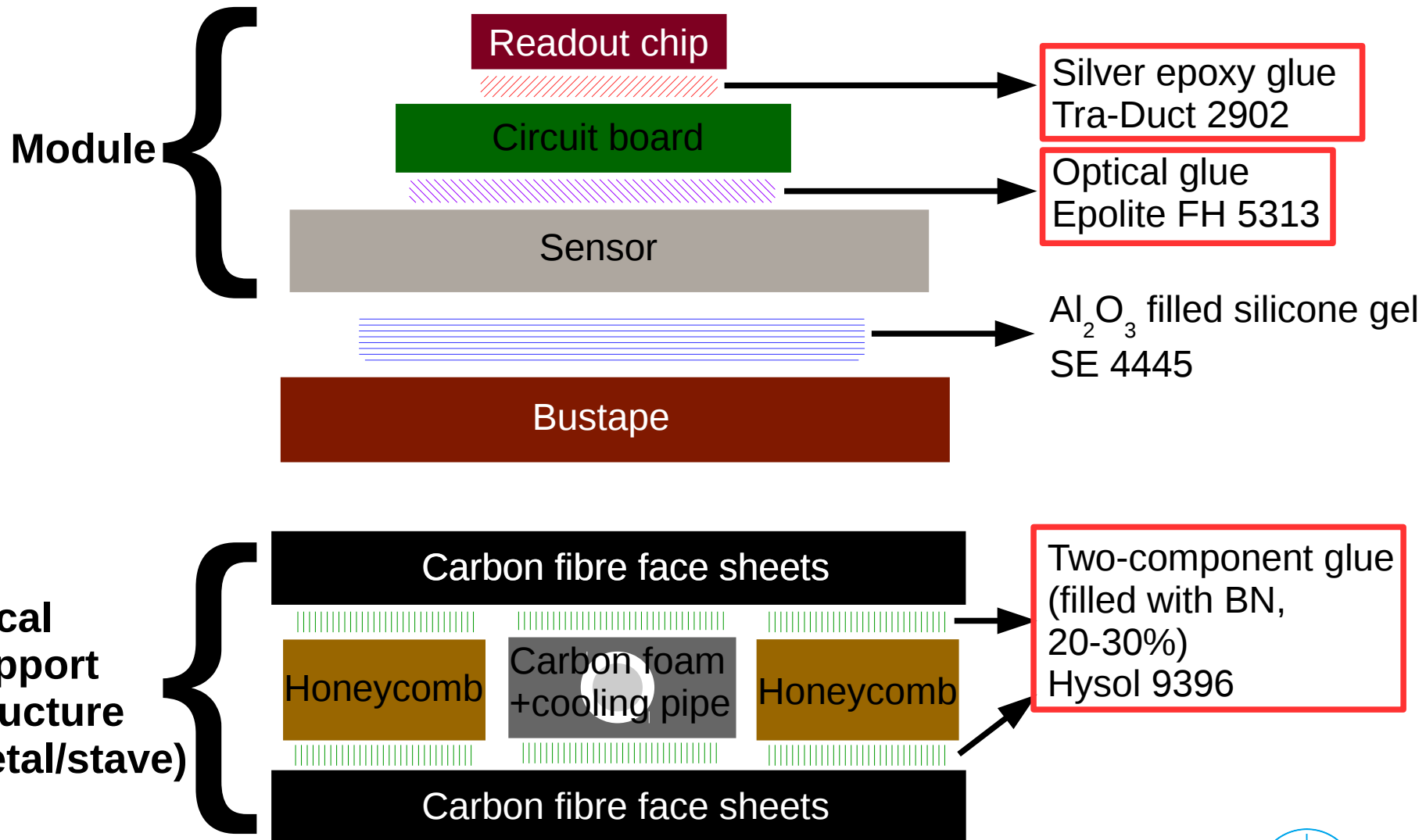
- > First hybrid built with UV cure glues used in module
  - Hybrid built using DYMAX 6-621 with glue dispenser (Birmingham)
- > No overheating of ASICs in operation
- > Noise plot comparable to modules built with previous glue
- > Decision about glue to be used in mass production will be made soon



## Glue characteristics

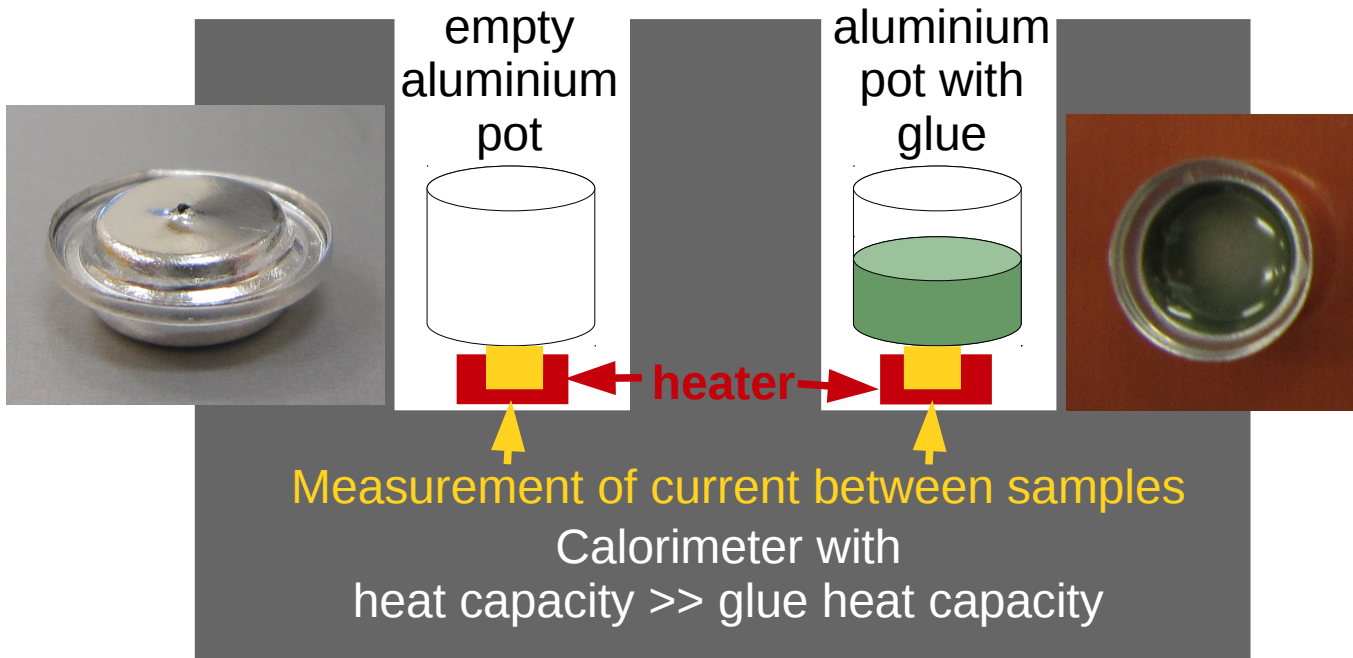


# Glues used in the detector



# Glue characteristics: Glass transition temperature

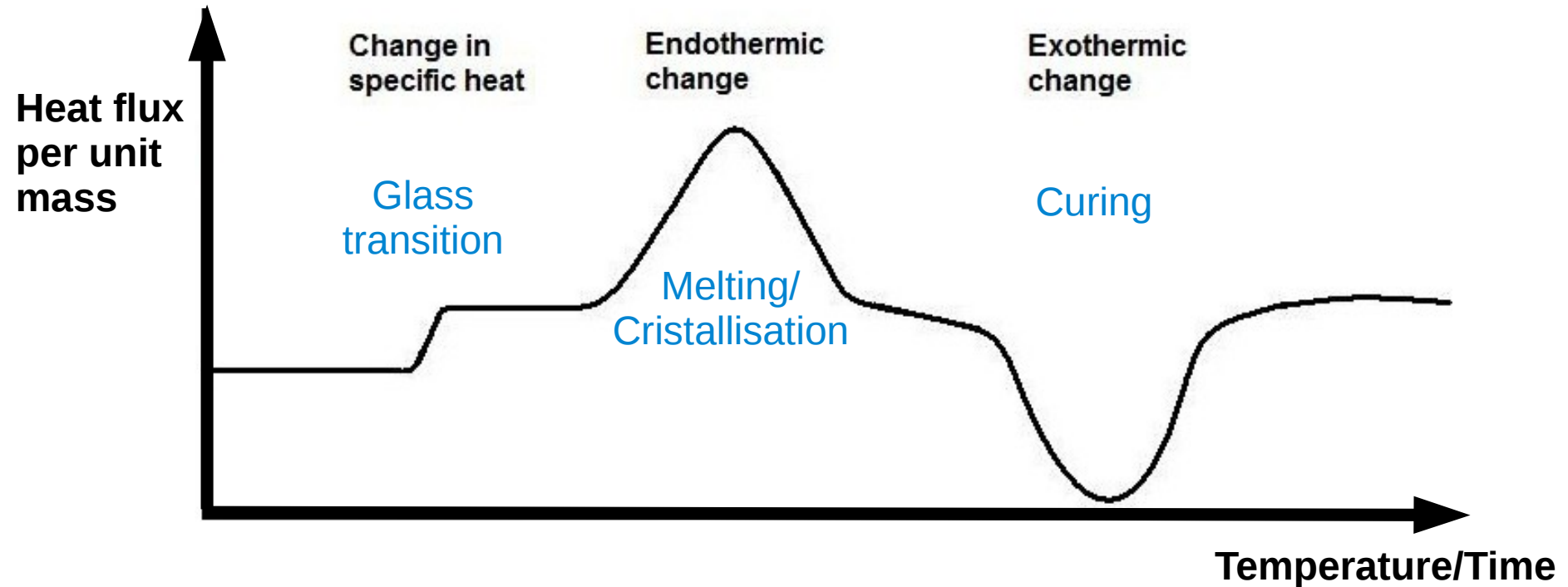
- > Glass transition temperature: temperature at which consistency changes from solid to glass-like
- > Should be well above operating temperature of detector
- > Can be measured with differential scanning calorimetry



Measurement of heat capacity of pot with glue compared to pot without glue, i.e. heat capacity of glue over range of temperature

→ find temperatures where heat capacity, i.e. glue consistency changes

# Glue characteristics: Differential scanning calorimetry



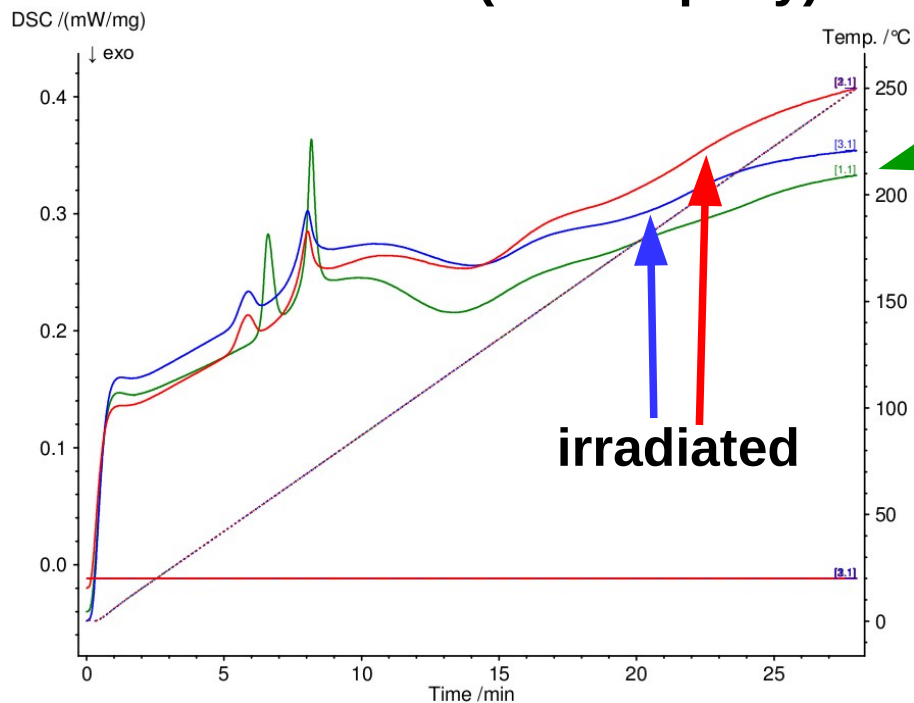
## > Performed for

- Glues currently used in module production (silver epoxy glue, optical glue)
- UV cure glues (possible replacement candidates)
- Hysol (used in support structure) 0%, 10%, 20% and 30% filled

## > Before and after irradiation (compare glass transition temperatures)

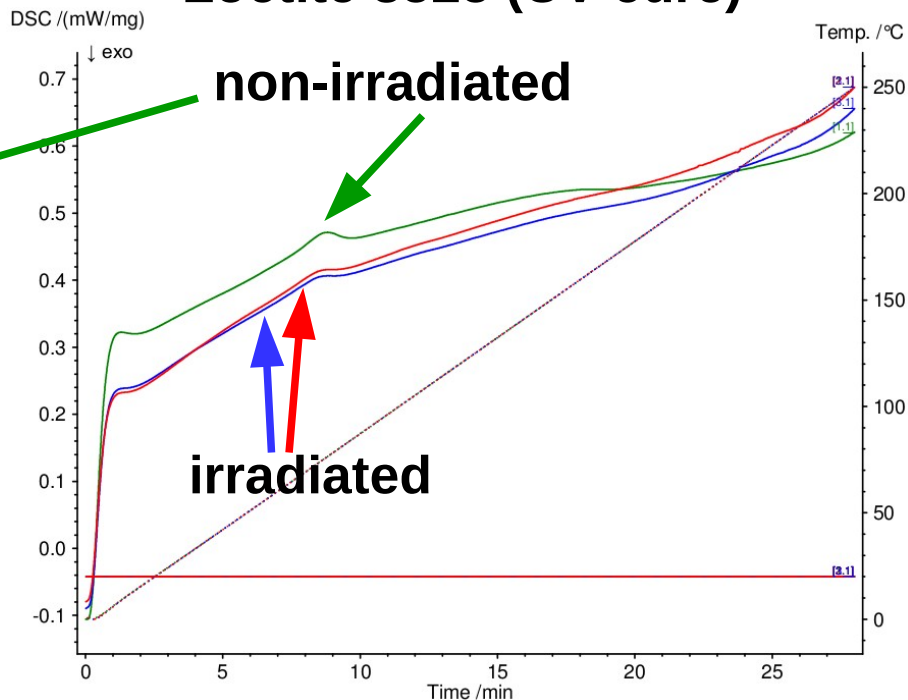
# Glue characteristics: changes by irradiation

## Tra-Duct 2902 (silver epoxy)



- > Irradiated samples show first endothermic peak at lower temperatures than non-irradiated samples
- > Peak's position moved from 46°C down to 39°C

## Loctite 3525 (UV cure)



- > Endothermic peak at same positions for irradiated and non-irradiated samples
- > Peak well above detector's working temperature (at 68°C)



# Glue characteristics: degree of curing

Information found in calorimetry

- > By comparing heat quantity released by uncured glue and cured glue curing grade can be determined
- > Degree of curing corresponds to quality of glue connection (strength)

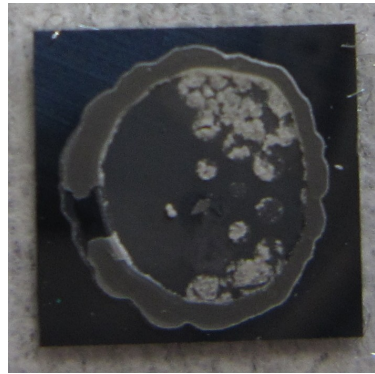
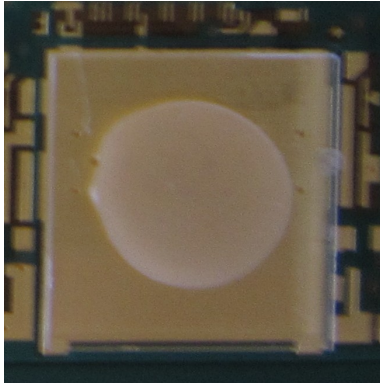
	0% BN	10% BN	20% BN	30% BN
Heat released from uncured glue [J/g]	-576,8	-546,2	-456,8	-403,7
Curing degree after 1 hour @ 60°C [%]	75,7	78,1	75,5	76,1
Curing degree after 3 days @ 20°C [%]	97,6	77,0	74,2	68,8

- > Glue cured in oven shows lower curing degree than glue cured at room temperature
- > For higher percentages of boron nitride filling glues cured in oven show higher curing degree



# Glue characteristics: structure changes by irradiation

- > Previous investigations of irradiated glue samples: thermo-mechanical (changes in thermal conduction, strength)
- > Now: investigation of chemical/microscopical properties



- > Currently: investigation of structure changes in glues caused by different types of irradiation
  - 3 most promising UV cure glues, silver epoxy glue and optical glue
  - 23 MeV protons, 800-900 MeV protons, reactor neutrons
  - 4 fluences each ( $1 \cdot 10^{15} \text{ n}_{\text{eq}}/\text{cm}^2$  to  $4 \cdot 10^{15} \text{ n}_{\text{eq}}/\text{cm}^2$ )
- > Investigate structure changes using Raman-spectroscopy (or combined Raman-REM?)

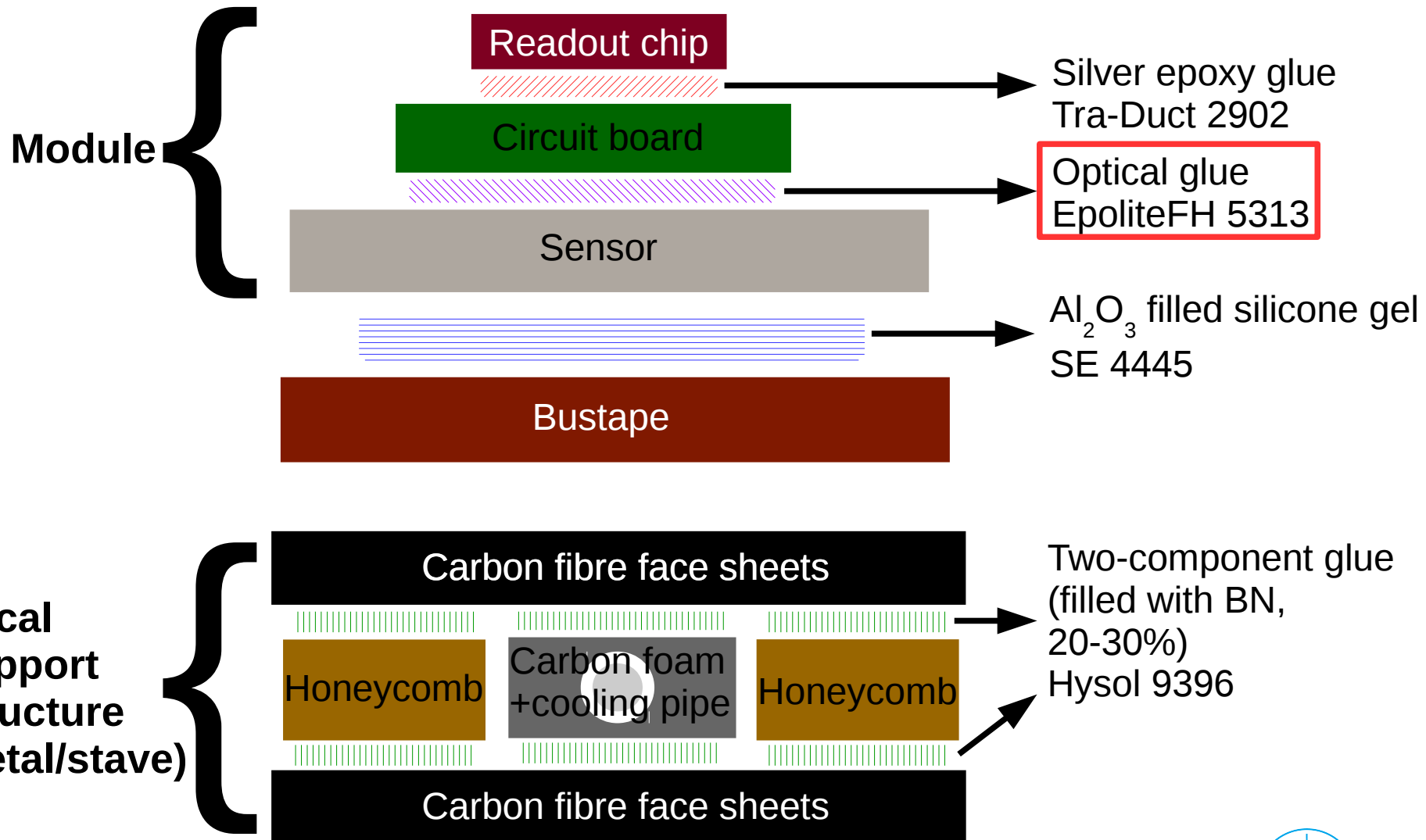
In progress

Next steps

## UV cure glue as replacement for optical glue on sensor



# Glues used in the detector



# UV cure glues between hybrids and sensor: why?

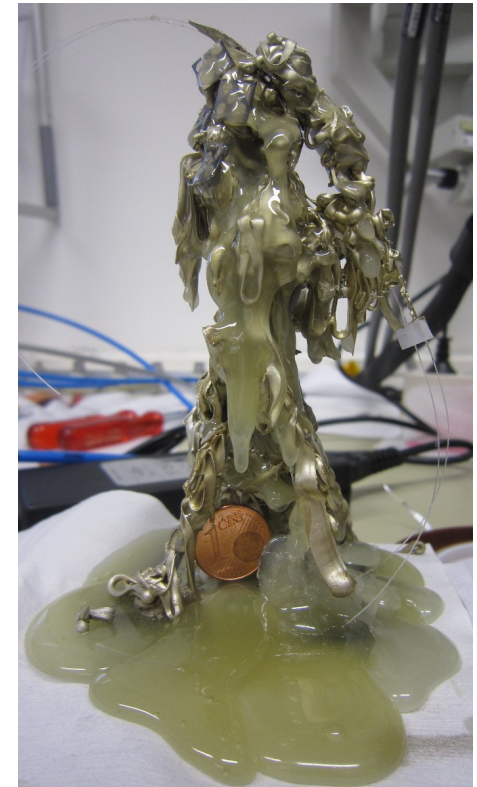
> Glue currently used between hybrid and sensor:  
Epolite FH-5313 (two-component non-conductive epoxy)

> Practical issues:

- long curing time (24 hrs)
- very brittle after curing

> Organisational issues:

- one component changed since use in Atlas SCT
- not sold to German companies (export regulations)
- most of it wasted
- expensive ( $\approx 200.000$  € for 10.000 modules)



# UV cure glues between hybrids and sensor: why?

> Glue currently used between hybrid and sensor:  
Epolite 5313 (two-component non-conductive epoxy)

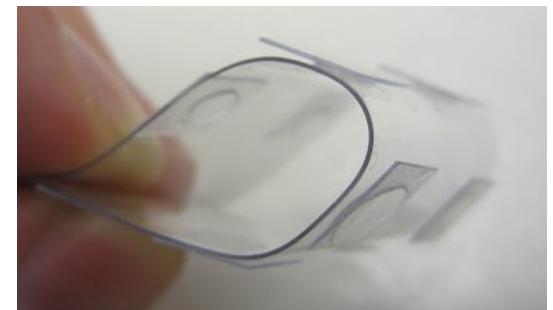
> Whereas for UV cure glues ...

> Practical issues:

- long curing time (24 hrs) short curing time (5 min)
- very brittle after curing flexible after curing

> Organisational issues:

- one component changed since use in Atlas
- not sold to German companies (export regulations) can be ordered everywhere
- most of it wasted **very cost-efficient**
- expensive ( $\approx 200.000$  € for 10.000 modules) ( $\approx 5.000$  € for 10.000 modules)



# UV cure glues between hybrid and sensor: glues

> UV cure glue candidates (same as before)

> LOCTITE 3525

> DYMAX 6-621

> DYMAX 3013

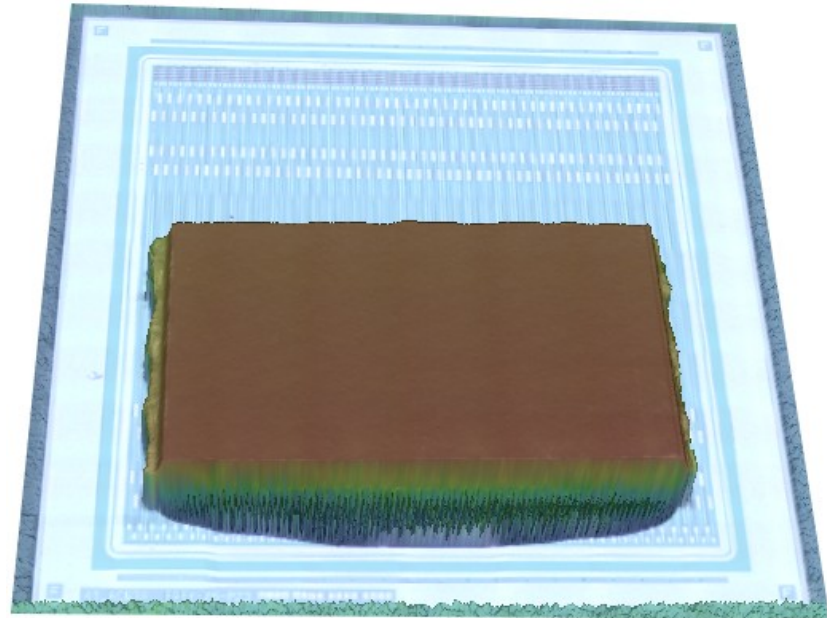
compared to Epolite FH-5313

> For tests:

applied 2.5  $\mu$ l of glue to sensor

piece of FR4 (without copper, covered with solder resist similar to hybrids) placed on top

cured with UV LEDs for 10 minutes



# UV cure glues between hybrid and sensor: tests

- > Possible effects of glue+FR4 on a sensor we considered most important
- > Curing (volume loss → contraction) might cause tension on sensor
- > Glue might chemically react with sensor (corrosion/diffusion)
- > Outgassing (curing/ageing) might lead to chemical reaction of sensor
- > Irradiation (compare blank and Epolite minis with UV cure glue minis)
  - With 23 MeV protons (KIT)
  - With 900 MeV protons (Los Alamos)
  - With reactor neutrons (Ljubljana)
- > Thermal cycling
- > Thermal cycling + irradiation (with 23 MeV protons)

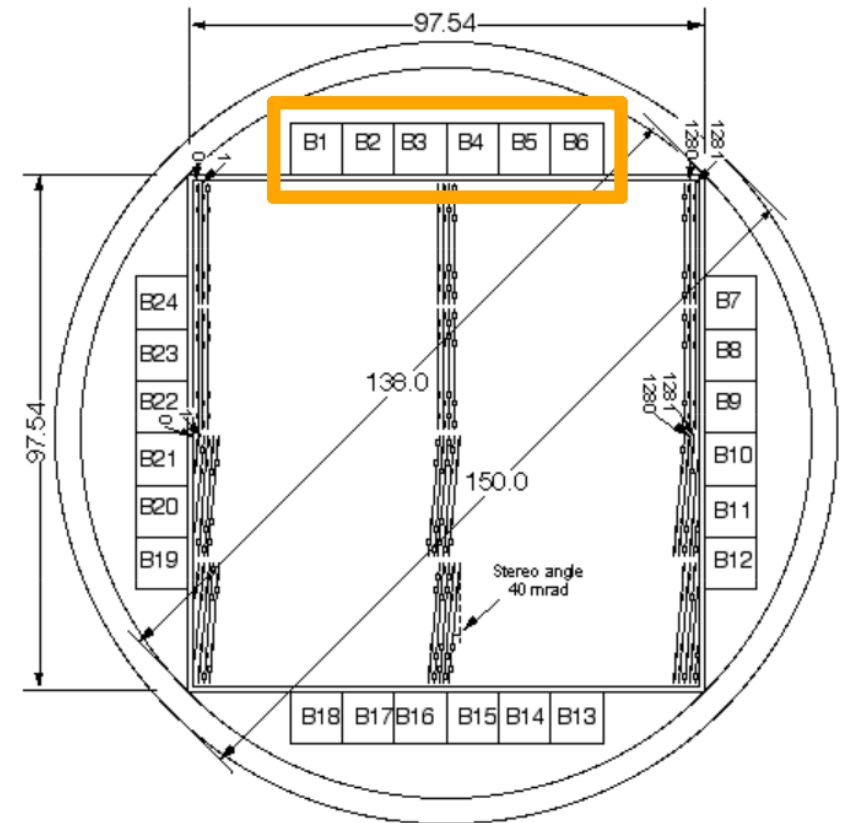
**In progress**





# UV cure glues between hybrid and sensor: measurements

- > Investigate effects of glue on sensor using silicon strip sensor prototype miniatures
- >  $I_V/C_V/C_{int}$ ,  $R_{int}$  before gluing, after gluing, after treatment
- > Laser microscope images (monitor corrosive effects)
- > For good sensors: connect to AliBaVa test setup (DESY test beam)
- > After performing every possible test: measure shear strength



Next steps

# UV cure glues between hybrid and sensor: problem

- > Every test to be performed for four glues (original + 3 UV cure)
- > Irradiation and ageing require additionally blank sensor (reference)
- > For (less than?) a minimum of statistics: two sensors per glue and test
- > Each test requires 8-10 mini sensors
  
- > Problem: miniature sensors were created for tests of different realisations of new n-in-p-sensor-architecture (p-stop, p-spray, ...)
  
- > We have 90 Atlas miniature sensors ...

BUT



# UV cure glues between hybrid and sensor: problem

> They are very different

	FZ1		FZ2	
	32		58	
	spray	no spray	spray	no spray
	18	14	15	43
BZ1 (no p-stop)	-	3	-	8
BZ2 (common p-stop)	3	-	4	4
BZ3 (individual p-stop)	5	-	1	5
BZ4 (different punch-through)	6	11	2	12
BZ5 (underhanging strip metal)	-	-	5	5
BZ6 (different strip pitch)	4	-	3	9

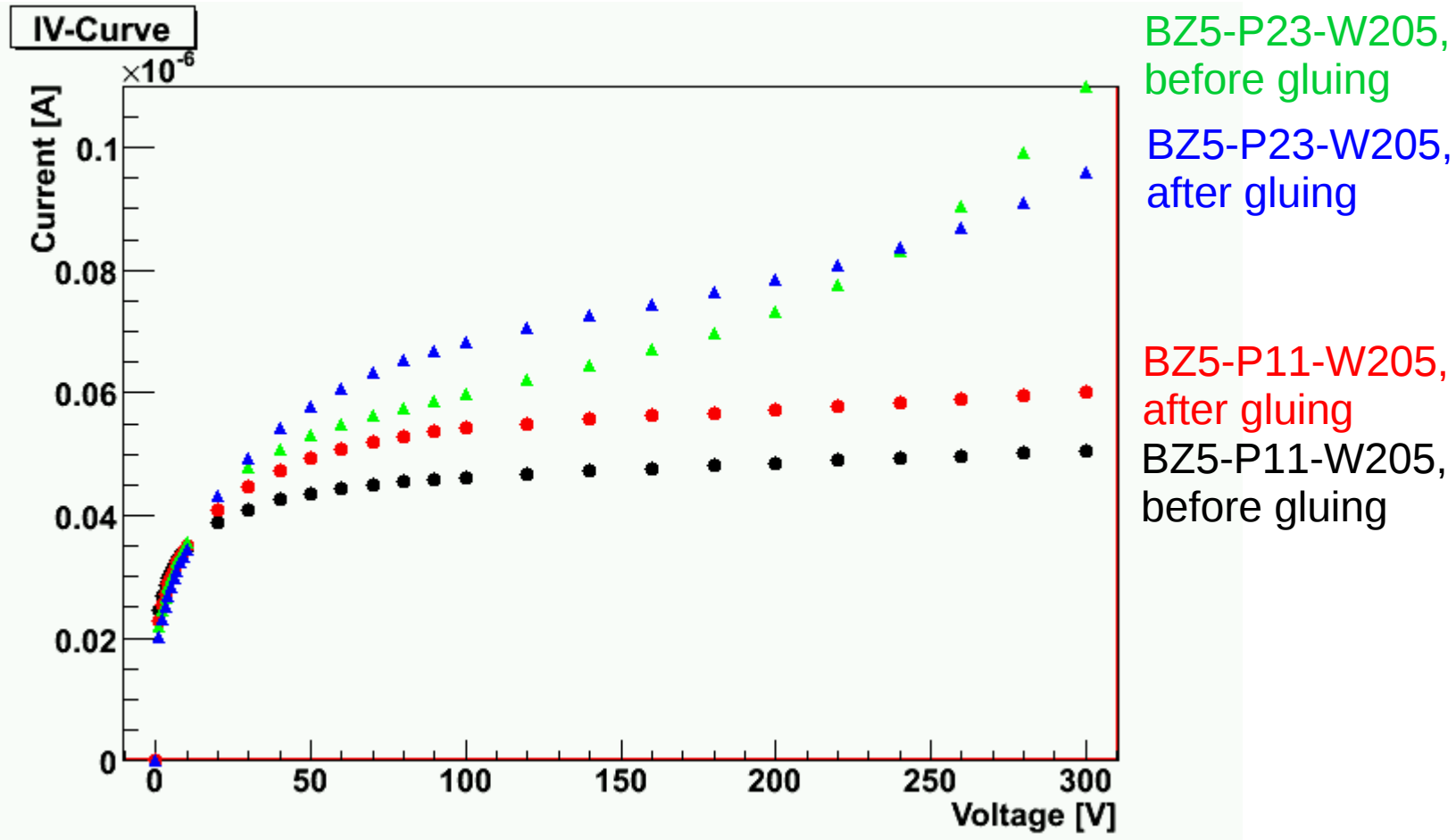
> hardly enough mini sensors of any type for test with 8-10 minis

> combination of similar types required (comparability?)



# UV cure glues between hybrid and sensor: problem

- On top of everything else:  
sensors which should be the same ...



# UV cure glues between hybrid and sensor: problem

- > So what can we learn from these studies?
  - Changes in a sensor from blank → glued → irradiated for every glue
  - Comparison between different glues difficult for sensors already show large differences between similar types
  - We will be able to identify serious problems
  - We might find a spread in results for the same glue
    - eliminate glues with serious issues, select candidate(s) for prototype module
  
- > In parallel: investigate sensor performance changes caused by gluing hybrid on top (using current glue)
  - gain better understanding of effects of gluing on silicon
  
- > Collect knowledge for first module to be built with convincing UV cure glue

Next steps



# Conclusion

- > Studies to replace silver epoxy glue with UV cure glue almost concluded
- > First prototypes built with good test results
- > Use for mass production (dispensing systems) under investigation
  
- > Studies about changes of glue characteristics caused by irradiation ongoing
  
- > Investigation of use of UV cure glue on sensor ongoing
  
- > PETTL has enabled these studies: thank you very much!

